

**150V N-Ch Power MOSFET**
**Feature**

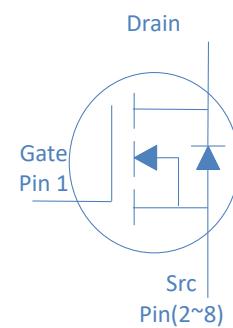
- ◊ High Speed Power Smooth Switching
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free

$V_{DS}$	150	V
$R_{DS(on),TYP}$	TOLL	4.8 mΩ
$I_D$ (Silicon Limited)	168	A

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control

Part Number	Package	Marking
HGT055N15S	TOLL	GT055N15S


**Absolute Maximum Ratings at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ\text{C}$	168	A
		$T_C=100^\circ\text{C}$	119	
Drain to Source Voltage	$V_{DS}$	-	150	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	550	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.4\text{mH}, T_C=25^\circ\text{C}$	720	mJ
Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	357	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\Theta JC}$	0.42	°C/W
Thermal Resistance Junction-Ambient	$R_{\Theta JA}$	60	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

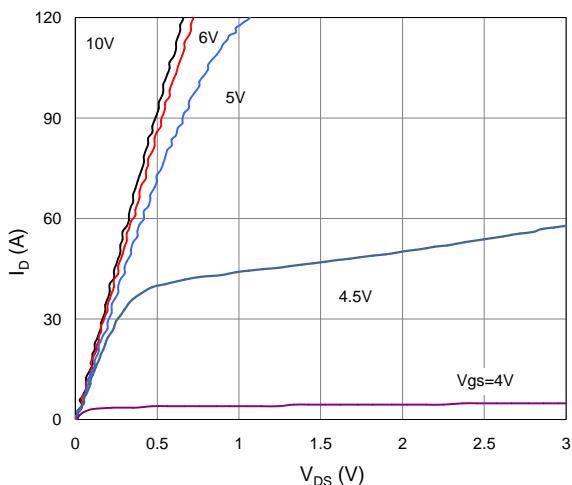
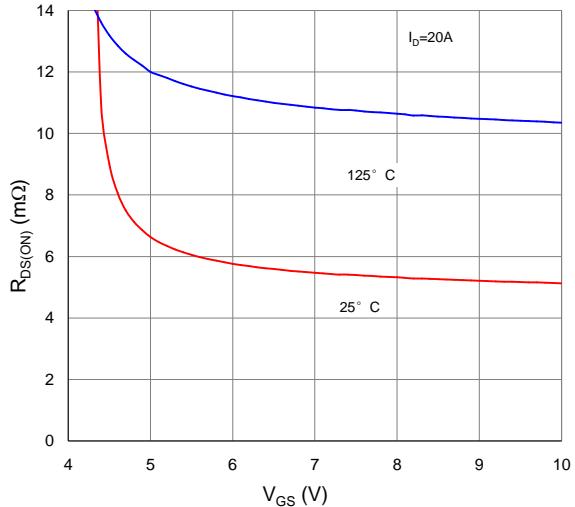
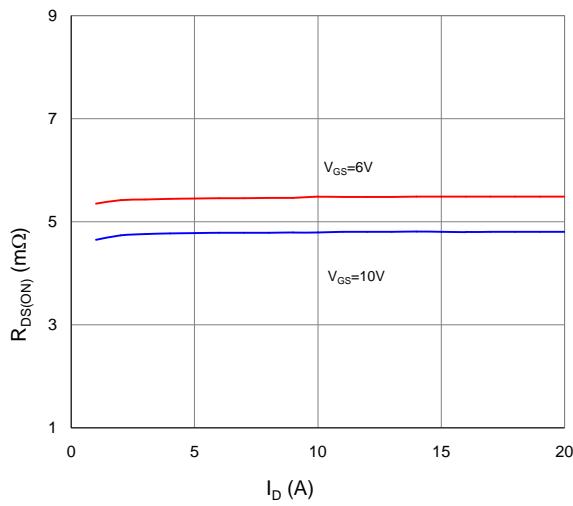
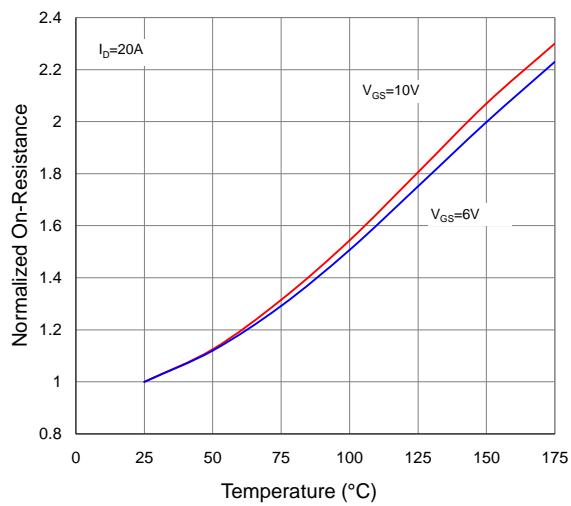
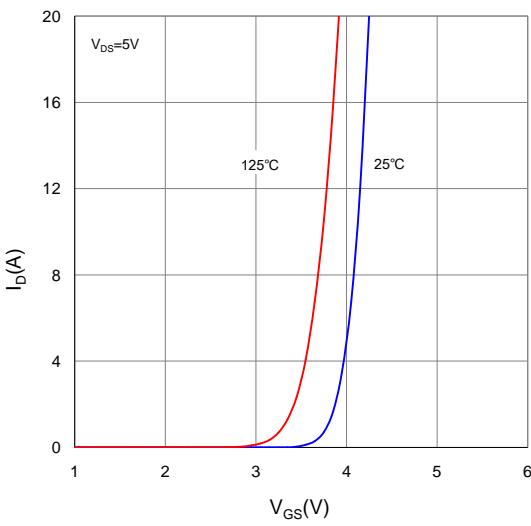
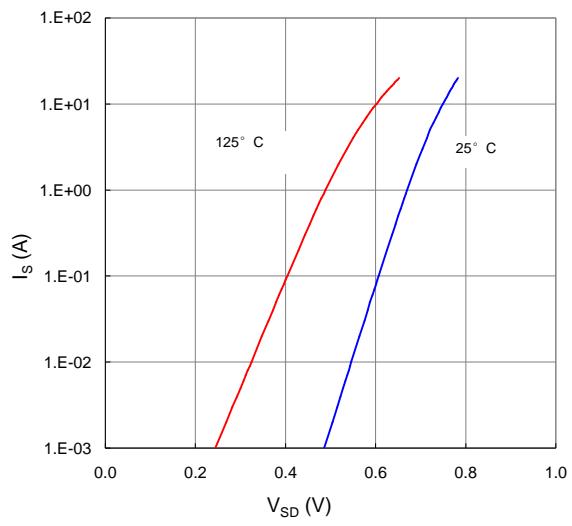
Parameter	Symbol	Conditions	Value			Unit		
			min	typ	max			
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	150	-	-	V		
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2	3	4			
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$		
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=100^\circ\text{C}$	-	-	100			
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA		
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	TOLL		-	4.8	5.5	$\text{m}\Omega$
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	80	-	S		
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	2.7	-	$\Omega$		

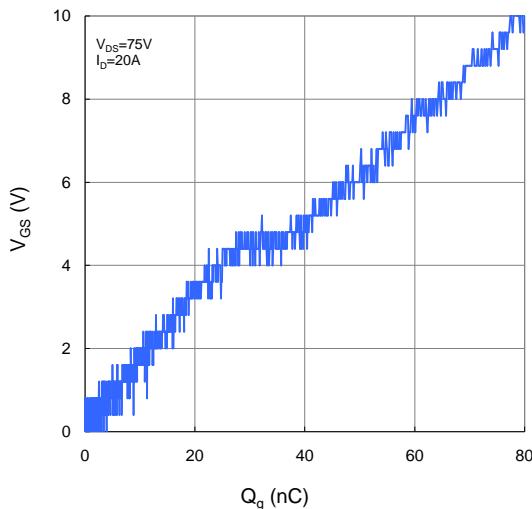
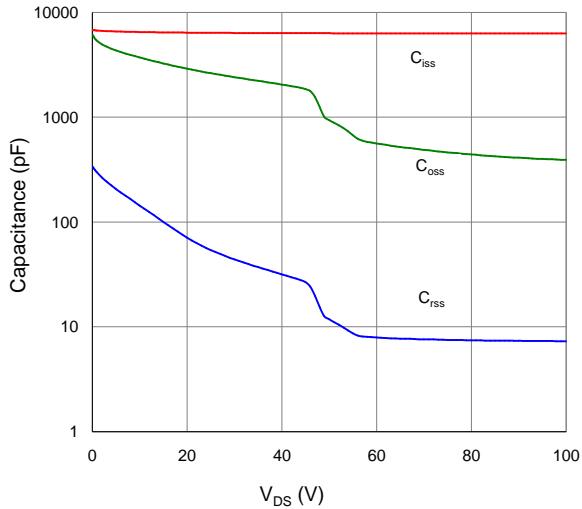
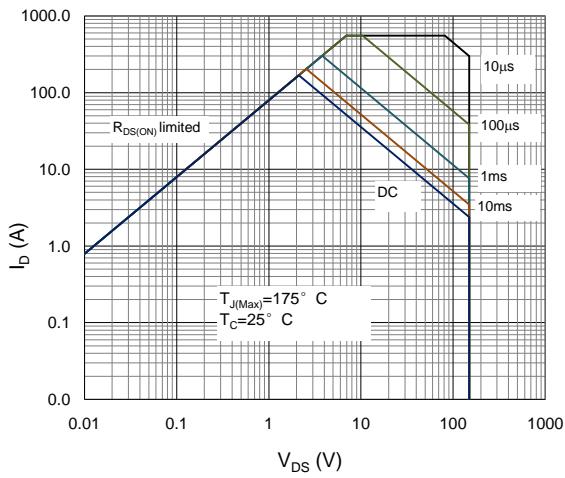
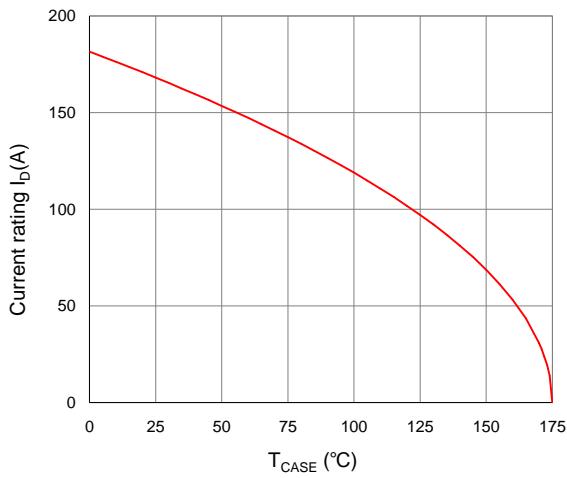
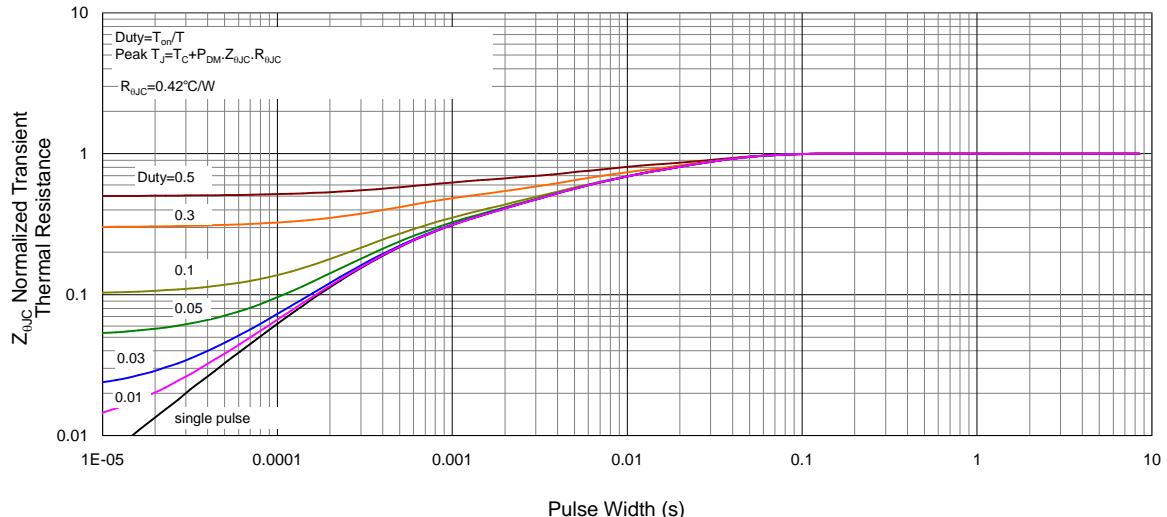
**Dynamic Characteristics**

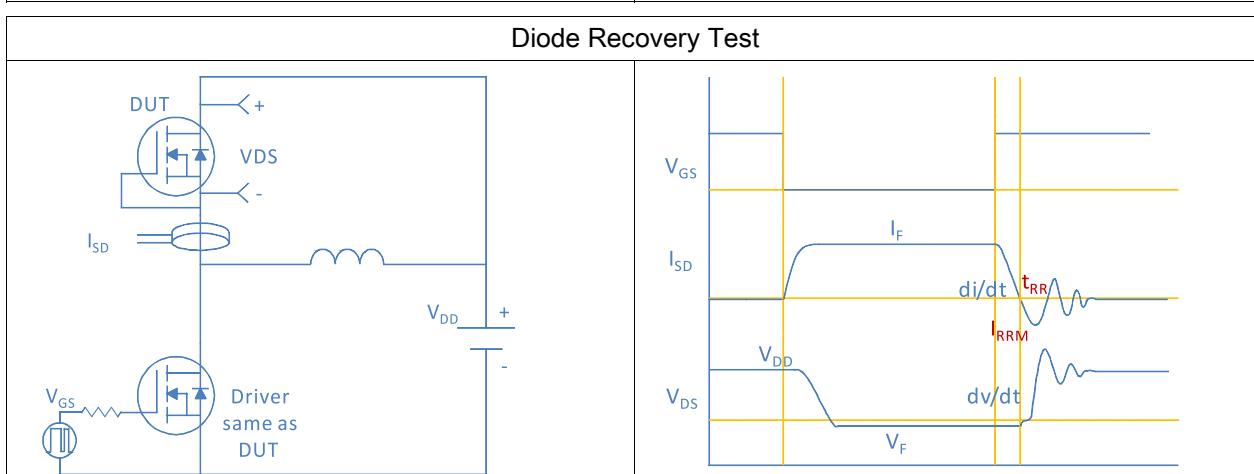
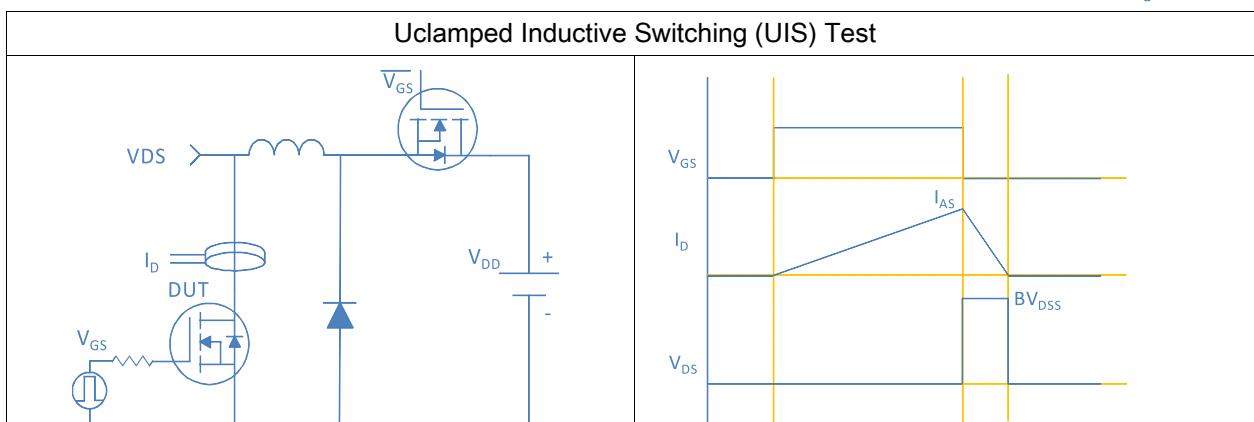
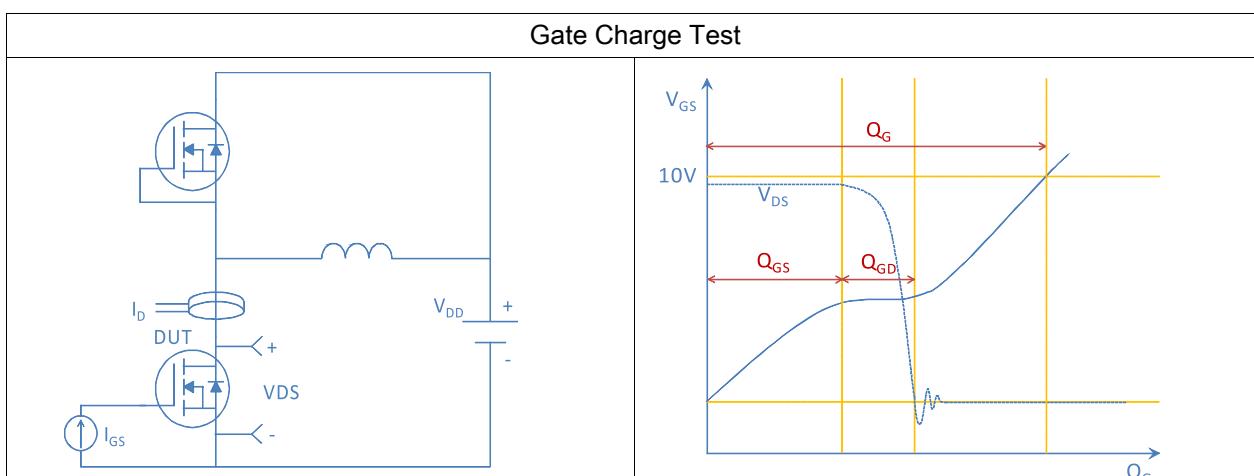
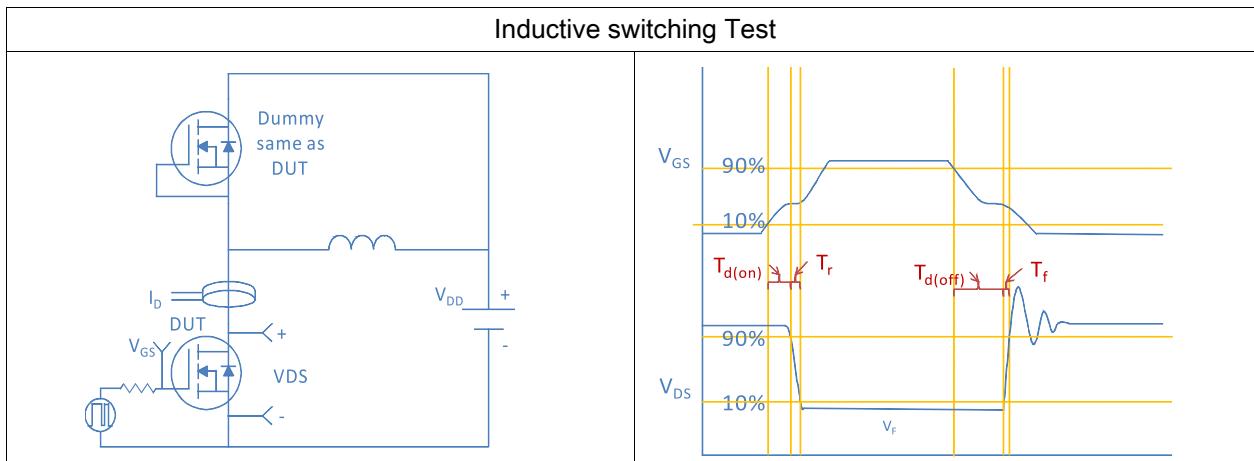
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=75\text{V}, f=1\text{MHz}$	-	6328	-	pF
Output Capacitance	$C_{\text{oss}}$		-	463	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	7.5	-	
Total Gate Charge	$Q_g$	$V_{\text{DD}}=75\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	80	-	nC
Gate to Source Charge	$Q_{\text{gs}}$		-	28	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	12	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=75\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	27	-	ns
Rise time	$t_r$		-	21	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	38	-	
Fall Time	$t_f$		-	14	-	

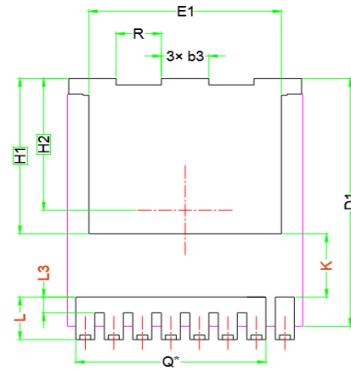
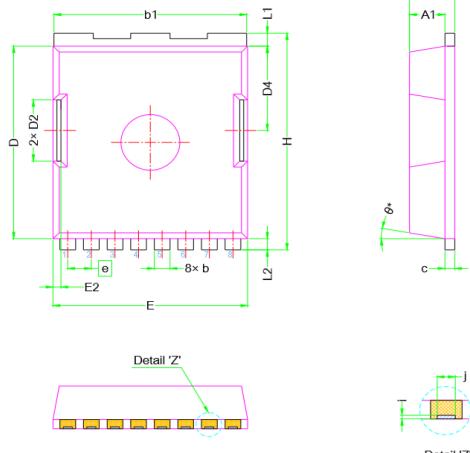
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=75\text{V}, I_F=20\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	80	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	160	-	nC

**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case**




**TOLL,8 leads**


SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
A1	1.70	1.80	1.90
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b3	1.90	2.00	2.10
c	0.40	0.50	0.60
D	10.28	10.38	10.48
D1	10.98	11.08	11.18
D2	3.20	3.30	3.40
D4	4.45	4.55	4.65
E	9.80	9.90	10.00
E1	8.00	8.10	8.20
E2	0.30	0.40	0.50
e	1.20 BSC		
H	11.58	11.68	11.78
H1	6.95 BSC		
H2	5.89 BSC		
i	0.10 REF.		
j	0.46 REF.		
K	2.80 REF.		
L	1.60	1.90	2.10
L1	0.60	0.70	0.80
L2	0.50	0.60	0.70
L3	0.60	0.70	0.80
N	8		
Q	6.80 REF.		
R	1.80	1.90	2.00
$\theta$	10° REF.		